



MIRO 3-3I610DW (2 Layer)

Fanless Embedded Computer with 6th/7th Gen Intel® Skylake-U / Kaby Lake-U i7 / i5 / i3 processor

Features:

- 6th / 7th Gen Intel® Skylake-U / Kaby Lake-U i7 / i5 / i3 CPU
- 2 x DDR4 SODIMM socket, Max. 64GB
- 5 x GbE, 2 x COM, 2 x HDMI, 4 x USB
- Wide Range 9~36V DC input
- 2 x Mini PCIe, 1 x Nano SIM
- DIN Rail mountable (with optional Kit)

Specifications :

Motherboard	3I610DW	
CPU	Intel® Skylake-U / Kaby Lake-U i7 / i5 / i3 CPU	
Chipset	Intel Skylake-U / Kaby Lake-U SoC	
Memory	2 x DDR4 SODIMM socket, Max. 64GB	
Storage	mSATA, HDD / SSD*	
Expansion slots	1 x Full-size Mini PCIe (USB / mSATA)	
	1 x Full-size Mini PCIe (PCIe / USB 3.0 / USB 2.0)	
	1 x Nano SIM	
I/O ports	Network	5 x Intel GbE
	USB	4 x USB 3.0
	Serial ports	2 x COM
	Display	2 x HDMI
	GPIO	DI / DO (optional)
Optional Modules & Accessory	GPS, Bluetooth, WiFi, 4G LTE, DI/O, Isolated COM	
	*VESA Mount Kit, *DIN Rail Mounting Kit	
	*Wall Mount Kit,	
	*SATA Kit *External Power Adapter	
OS Support	7th Generation Intel® Core™ Processor family: Kaby Lake Windows® 10 IOT (64bit), Ubuntu 16.04.3 above, Fedora 26 above, CentOS 7.4 above 6th Generation Intel® Core™ Processor family: Skylake Windows® 10 IOT (64bit) Windows® 8.1 (64bit) Windows® Embedded 8 Standard (64bit) Windows® 7 (64bit) Windows® Embedded Sta 7 (64bit) Ubuntu 16.04.3 above, Fedora 26 above, CentOS 7.4 above	

Mechanical

Dimensions	178W x 116D x 72.9H mm
Weight	1.5 kg
Mounting	Wall Mount*, DIN Rail Mount*, VESA Mount*

Power

DC input	+9~36V
AC input	External adapter 100 / 240V

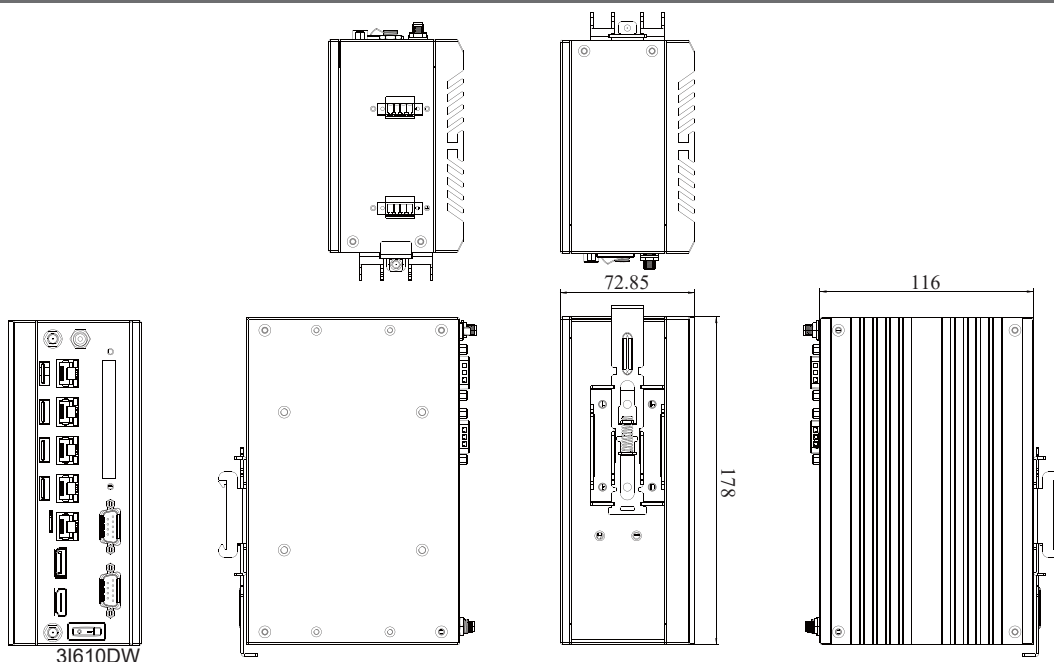
Environment

Operating Temp. (100% CPU usage)	-20°C to +60°C (Celeron 3955U)
	-20°C to +50°C (Core i5 6300U)
	-20°C to +50°C (Core i7 6600U)
	-20°C to +50°C (Core i3 6100U)
	*W / Industrial SSD
Storage Temp.	-20°C to +70°C
Relative Humidity	95% @ 40°C, non-condensing

Certification

CE / FCC, IEC / IECCE

Dimension



Specification are subject to change without prior notice. ODM / OEM is available.